

SECTION 270526 - GROUNDING AND BONDING FOR COMMUNICATIONS SYSTEMS

PART 1 - GENERAL

1.1 RELATED DOCUMENTS

- A. Drawings and general provisions of the Contract, including General and Supplementary Conditions and Division 01 Specification Sections, apply to this Section.

1.2 SUMMARY

- A. Section Includes:
 - 1. Grounding conductors.
 - 2. Grounding connectors.
 - 3. Grounding busbars.
 - 4. Grounding rods.
 - 5. Grounding labeling.

1.3 DEFINITIONS

- A. BCT: Bonding conductor for telecommunications.
- B. EMT: Electrical metallic tubing.
- C. TGB: Telecommunications grounding busbar.
- D. TMGB: Telecommunications main grounding busbar.

1.4 ACTION SUBMITTALS

- A. Product Data: For each type of product.
- B. Shop Drawings: For communications equipment room signal reference grid. Include plans, elevations, sections, details, and attachments to other work.

1.5 INFORMATIONAL SUBMITTALS

- A. As-Built Data: Plans showing as-built locations of grounding and bonding infrastructure, including the following:
 - 1. Ground rods.
 - 2. Ground and roof rings.
 - 3. BCT, TMGB, TGBs, and routing of their bonding conductors.

- B. Qualification Data: For installer, installation supervisor, and field inspector.
- C. Qualification Data: For testing agency and testing agency's field supervisor.
- D. Field quality-control reports.

1.6 CLOSEOUT SUBMITTALS

- A. Operation and Maintenance Data: For grounding to include in emergency, operation, and maintenance manuals.
 - 1. In addition to items specified in Section 017823 "Operation and Maintenance Data," include the following:
 - a. Result of the ground-resistance test, measured at the point of BCT connection.
 - b. Result of the bonding-resistance test at each TGB and its nearest grounding electrode.

1.7 QUALITY ASSURANCE

- A. Installer Qualifications: Cabling Installer must have personnel certified by BICSI on staff.

PART 2 - PRODUCTS

2.1 SYSTEM COMPONENTS

- A. Comply with J-STD-607-A.

2.2 CONDUCTORS

- A. Manufacturers: Subject to compliance with requirements, available manufacturers offering products that may be incorporated into the Work include, but are not limited to, the following:
 - 1. Harger Lightning and Grounding.
 - 2. Panduit Corp.
 - 3. Tyco Electronics Corp.
- B. Comply with UL 486A-486B.
- C. Insulated Conductors: Stranded copper wire, green or green with yellow stripe insulation, insulated for 600 V, and complying with UL 83.
 - 1. Ground wire for custom-length equipment ground jumpers shall be No. 6 AWG, 19-strand, UL-listed, Type THHN wire.

D. Bare Copper Conductors:

1. Solid Conductors: ASTM B 3.
2. Bonding Cable: 28 kcmils (14.2 sq. mm), 14 strands of No. 17 AWG conductor, and 1/4 inch (6.3 mm) in diameter.
3. Bonding Conductor: No. 4 or No. 6 AWG, stranded conductor.
4. Bonding Jumper: Tinned-copper tape, braided conductors terminated with two-hole copper ferrules; 1-5/8 inches (41 mm) wide and 1/16 inch (1.6 mm) thick.

2.3 CONNECTORS

- A. Irreversible connectors listed for the purpose. Listed by an NRTL as complying with NFPA 70 for specific types, sizes, and combinations of conductors and other items connected. Comply with UL 486A-486B.
- B. Basis-of-Design Product: Subject to compliance with requirements, provide product indicated on Drawings or comparable product by one of the following:
1. Burndy; Part of Hubbell Electrical Systems.
 2. Chatsworth Products, Inc.
 3. Harger Lightning and Grounding.
 4. Panduit Corp.
 5. Tyco Electronics Corp.
- C. Compression Wire Connectors: Crimp-and-compress connectors that bond to the conductor when the connector is compressed around the conductor. Comply with UL 467.
1. Electroplated tinned copper, C and H shaped.
- D. Busbar Connectors: Cast silicon bronze, solderless compression-type, mechanical connector; with a long barrel and two holes spaced on 5/8- or 1-inch (15.8- or 25.4-mm) centers for a two-bolt connection to the busbar.
- E. Welded Connectors: Exothermic-welding kits of types recommended by kit manufacturer for materials being joined and installation conditions.

2.4 GROUNDING BUSBARS

- A. Basis-of-Design Product: Subject to compliance with requirements, provide product indicated on Drawings or comparable product by one of the following:
1. Chatsworth Products, Inc.
 2. Harger Lightning and Grounding.
 3. Panduit Corp.
- B. TMGB: Predrilled, wall-mounted, rectangular bars of hard-drawn solid copper, 1/4 by 4 inches (6.3 by 100 mm) in cross section, length as indicated on Drawings. The busbar shall be NRTL listed for use as TMGB and shall comply with J-STD-607-A.

1. Predrilling shall be with holes for use with lugs specified in this Section.
 2. Mounting Hardware: Stand-off brackets that provide a **4-inch ((100-mm)) clearance to access the rear of the busbar. Brackets and bolts shall be stainless steel.**
 3. Stand-off insulators for mounting shall be Lexan or PVC. Comply with UL 891 for use in 600-V switchboards, impulse tested at 5000 V.
- C. Rack and Cabinet Grounding Busbars: Rectangular bars of hard-drawn solid copper, accepting conductors ranging from No. 14 to No. 2/0 AWG, NRTL listed as complying with UL 467, and complying with J-STD-607-A. Predrilling shall be with holes for use with lugs specified in this Section.
1. Cabinet-Mounted Busbar: Terminal block, with stainless-steel or copper-plated hardware for attachment to the cabinet.
 2. Rack-Mounted Horizontal Busbar: Designed for mounting in **19- or 23-inch (483- or 584-mm)** equipment racks. Include a copper splice bar for transitioning to an adjoining rack, and stainless-steel or copper-plated hardware for attachment to the rack.
 3. Rack-Mounted Vertical Busbar: **72 or 36 inches ((1827 or 914 mm) long, with)** stainless-steel or copper-plated hardware for attachment to the rack.

2.5 LABELING

- A. **Manufacturers:** Subject to compliance with requirements, available manufacturers offering products that may be incorporated into the Work include, but are not limited to, the following:
1. **Brother International Corporation.**
 2. **HellermannTyton.**
 3. **Panduit Corp.**
- B. Comply with TIA/EIA-606-A and UL 969 for a system of labeling materials, including label stocks, laminating adhesives, and inks used by label printers.
- C. Adhesive Film Label with Clear Protective Overlay: Machine printed, in black, by thermal transfer or equivalent process. Minimum letter height shall be **3/8 inch (10 mm)**. Overlay shall provide a weatherproof and UV-resistant seal for label.

PART 3 - EXECUTION

3.1 EXAMINATION

- A. Examine the ac grounding electrode system and equipment grounding for compliance with requirements for maximum ground-resistance level and other conditions affecting performance of grounding and bonding of the electrical system.
- B. Inspect the test results of the ac grounding system measured at the point of BCT connection.
- C. Prepare written report, endorsed by Installer, listing conditions detrimental to performance of the Work.

- D. Proceed with connection of the BCT only after unsatisfactory conditions have been corrected.

3.2 INSTALLATION

- A. Bonding shall include the ac utility power service entrance, the communications cable entrance, and the grounding electrode system. The bonding of these elements shall form a loop so that each element is connected to at least two others.
- B. Comply with NECA 1.
- C. Comply with J-STD-607-A.

3.3 APPLICATION

- A. Conductors: Install solid conductor for No. 8 AWG and smaller and stranded conductors for No. 6 AWG and larger unless otherwise indicated.
 - 1. The bonding conductors between the TGB and structural steel of steel-frame buildings shall not be smaller than No. 6 AWG.
 - 2. The bonding conductors between the TMGB and structural steel of steel-frame buildings shall not be smaller than No. 6 AWG.
- B. Conductor Terminations and Connections:
 - 1. Pipe and Equipment Grounding Conductor Terminations: Bolted connectors.
 - 2. Underground Connections: Welded connectors except at test wells and as otherwise indicated.
 - 3. Connections to Ground Rods at Test Wells: Bolted connectors.
 - 4. Connections to Structural Steel: Welded connectors.
- C. Conductor Support:
 - 1. Secure grounding and bonding conductors at intervals of not less than 36 inches ((900 mm).)
- D. Grounding and Bonding Conductors:
 - 1. Install in the straightest and shortest route between the origination and termination point, and no longer than required. The bend radius shall not be smaller than eight times the diameter of the conductor. No one bend may exceed 90 degrees.
 - 2. Install without splices.
 - 3. Support at not more than 36-inch (900-mm) intervals.
 - 4. Install grounding and bonding conductors in 3/4-inch (21-mm) PVC conduit until conduit enters a telecommunications room. The grounding and bonding conductor pathway through a plenum shall be in EMT. Conductors shall not be installed in EMT unless otherwise indicated.
 - a. If a grounding and bonding conductor is installed in ferrous metallic conduit, bond the conductor to the conduit using a grounding bushing that complies with

requirements in Section 270528 "Pathways for Communications Systems," and bond both ends of the conduit to a TGB.

3.4 GROUNDING BUSBARS

- A. Indicate locations of grounding busbars on Drawings. Install busbars horizontally, on insulated spacers **2 inches (50 mm)** minimum from wall, **12 inches (300 mm)** above finished floor unless otherwise indicated.
- B. Where indicated on both sides of doorways, route bus up to top of door frame, across top of doorway, and down; connect to horizontal bus.

3.5 CONNECTIONS

- A. Bond metallic equipment in a telecommunications equipment room to the grounding busbar in that room, using equipment grounding conductors not smaller than No. 6 AWG.
- B. Stacking of conductors under a single bolt is not permitted when connecting to busbars.
- C. Assemble the wire connector to the conductor, complying with manufacturer's written instructions and as follows:
 - 1. Use crimping tool and the die specific to the connector.
 - 2. Pretwist the conductor.
 - 3. Apply an antioxidant compound to all bolted and compression connections.
- D. Primary Protector: Bond to the TMGB with insulated bonding conductor.
- E. Interconnections: Interconnect all TGBs with the TMGB with the telecommunications backbone conductor. If more than one TMGB is installed, interconnect TMGBs using the grounding equalizer conductor. The telecommunications backbone conductor and grounding equalizer conductor size shall not be less than **2 kcmils/linear foot (1 sq. mm/linear meter)** of conductor length, up to a maximum size of No. 3/0 AWG unless otherwise indicated.
- F. Telecommunications Enclosures and Equipment Racks: Bond metallic components of enclosures to the telecommunications bonding and grounding system. Install vertically mounted rack grounding busbar unless the enclosure and rack are manufactured with the busbar. Bond the equipment grounding busbar to the TGB No. 2 AWG bonding conductors.
- G. Structural Steel: Where the structural steel of a steel frame building is readily accessible within the room or space, bond each TGB and TMGB to the vertical steel of the building frame.
- H. Electrical Power Panelboards: Where an electrical panelboard for telecommunications equipment is located in the same room or space, bond each TGB to the ground bar of the panelboard.
- I. Shielded Cable: Bond the shield of shielded cable to the TGB in communications rooms and spaces. Comply with TIA/EIA-568-B.1 and TIA/EIA-568-B.2 when grounding screened, balanced, twisted-pair cables.

- J. Rack- and Cabinet-Mounted Equipment: Bond powered equipment chassis to the cabinet or rack grounding bar. Power connection shall comply with NFPA 70; the equipment grounding conductor in the power cord of cord- and plug-connected equipment shall be considered as a supplement to bonding requirements in this Section.
- K. Access Floors: Bond all metal parts of access floors to the TGB.
- L. Equipment Room Signal Reference Grid: Provide a low-impedance path between telecommunications cabinets, equipment racks, and the reference grid, using No. 6 AWG bonding conductors.
 - 1. Install the conductors in grid pattern on 4-foot (1200-mm) centers, allowing bonding of one pedestal from each access floor tile.
 - 2. Bond the TGB of the equipment room to the reference grid at two or more locations.
 - 3. Bond all conduits and piping entering the equipment room to the TGB at the perimeter of the room.

3.6 GROUNDING UNDERGROUND DISTRIBUTION SYSTEM COMPONENTS

- A. Duct-Bank Grounding Conductor: Bury 12 inches (300 mm) above duct bank when indicated as part of duct-bank installation.
- B. Comply with IEEE C2 grounding requirements.
- C. Grounding Manholes and Handholes: Install a driven ground rod through manhole or handhole floor, close to wall, and set rod depth so 4 inches (100 mm) extends above finished floor. If necessary, install ground rod before manhole is placed and provide No. 1/0 AWG bare, tinned-copper conductor from ground rod into manhole through a waterproof sleeve in manhole wall. Protect ground rods passing through concrete floor with a double wrapping of pressure-sensitive insulating tape or heat-shrunk insulating sleeve from 2 inches (50 mm) above to 6 inches (150 mm) below concrete. Seal floor opening with waterproof, nonshrink grout.
- D. Grounding Connections to Manhole Components: Bond exposed-metal parts such as inserts, cable racks, pulling irons, ladders, and cable shields within each manhole or handhole, to ground rod or grounding conductor. Make connections with No. 4 AWG minimum, bonding conductor. Train conductors level or plumb around corners and fasten to manhole walls. Connect grounding conductors to cable armor and cable shields according to written instructions by manufacturer of splicing and termination kits.

3.7 IDENTIFICATION

- A. Labels shall be preprinted or computer-printed type.
 - 1. Label TMGB(s) with "fs-TMGB," where "fs" is the telecommunications space identifier for the space containing the TMGB.
 - 2. Label TGB(s) with "fs-TGB," where "fs" is the telecommunications space identifier for the space containing the TGB.

3. Label the BCT and each telecommunications backbone conductor at its attachment point: "WARNING! TELECOMMUNICATIONS BONDING CONDUCTOR. DO NOT REMOVE OR DISCONNECT!"

3.8 FIELD QUALITY CONTROL

- A. Testing Agency: Engage a qualified testing agency to perform tests and inspections.
- B. Perform tests and inspections.
- C. Tests and Inspections:
 1. Inspect physical and mechanical condition. Verify tightness of accessible, bolted, electrical connections with a calibrated torque wrench according to manufacturer's written instructions.
 2. Test the bonding connections of the system using an ac earth ground-resistance tester, taking two-point bonding measurements in each telecommunications equipment room containing a TMGB and a TGB and using the process recommended by BICSI TDMM. Conduct tests with the facility in operation.
 - a. Measure the resistance between the busbar and the nearest available grounding electrode. The maximum acceptable value of this bonding resistance is 100 milliohms.
 3. Test for ground loop currents using a digital clamp-on ammeter, with a full-scale of not more than 10 A, displaying current in increments of 0.01 A at an accuracy of plus/minus 2.0 percent.
 - a. With the grounding infrastructure completed and the communications system electronics operating, measure the current in every conductor connected to the TMGB. Maximum acceptable ac current level is 1 A.
- D. Excessive Ground Resistance: If resistance to ground at the BCT exceeds 5 ohms, notify Architect promptly and include recommendations to reduce ground resistance.
- E. Grounding system will be considered defective if it does not pass tests and inspections.
- F. Prepare test and inspection reports.

END OF SECTION 270526